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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20095**

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**Issue Date:** 30-May-2013

**TITLE:** (CHIP) Production assembly process will be transferred from SANYO-HANYU site to SSMP

**PROPOSED FIRST SHIP DATE:** 6-Sep-2013

**AFFECTED CHANGE CATEGORY(S):** Assembly site

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or [Takehito.Tsukui@onsemi.com](mailto:Takehito.Tsukui@onsemi.com)

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** No Need Assembly Only

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

Production assembly process will be transferred from SANYO-HANYU (CHIP) site to SSMP (Sanyo Semiconductor Manufacturing Philippines Corporation).

There will be no other changes that include the electrical characteristics specification other than mentioned above.



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**RELIABILITY DATA SUMMARY:** N/A

**ELECTRICAL CHARACTERISTIC SUMMARY:**

There are not any other changes including electric characteristic specifications.

**CHANGED PART IDENTIFICATION:**

Products manufactured at SSMP will be marked with 'L7' preceding the Lot No. on shipping label.

**List of affected General Parts:**

LC70615C-4-W1

LC706161CM

LC706171CM